

MOSFET – Power, Single N-Channel, STD Gate, SO8FL

80 V, 2.1 mΩ, 181 A

NTMFS2D5N08X

Features

- Low QRR, Soft Recovery Body Diode
- Low R_{DS(on)} to Minimize Conduction Losses
- Low QG and Capacitance to Minimize Driver Losses
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Synchronous Rectification (SR) in DC-DC and AC-DC
- Primary Switch in Isolated DC-DC Converter
- Motor Drives

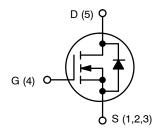
MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DSS}	80	V
Gate-to-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _C = 25°C	I _D	181	Α
(Note 1)	T _C = 100°C		128	
Power Dissipation (Note 1)	T _C = 25°C	P_{D}	148	W
Pulsed Drain Current	T _C = 25°C,	I _{DM}	761	Α
Pulsed Source Current (Body Diode)	t _p = 100 μs	I _{SM}	761	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55 to +175	°C
Source Current (Body Diode)		Is	224	Α
Single Pulse Avalanche Energy (I _{PK} = 55 A) (Note 3)		E _{AS}	151	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C

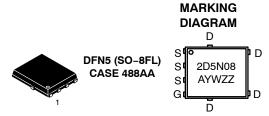
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown.
 They are not constants and are only valid for the particular conditions noted.
- Actual continuous current will be limited by thermal and electromechanical application board design
- 3. E_{AS} of 151 mJ is based on started T_J = 25°C, I_{AS} = 55 A, V_{DD} = 64 V, V_{GS} = 10 V, 100% avalanche tested

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
80 V	2.1 mΩ @ 10 V	181 A



N-CHANNEL MOSFET



2D5N08 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping [†]
NTMFS2D5N08XT1G	DFN5 (Pb-Free)	1500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	1.01	°C/W
Thermal Resistance, Junction-to-Ambient (Notes 4, 5)	$R_{ heta JA}$	39	

^{4.} Surface mounted on FR4 board using a 1 in^2 , 1 oz. Cu pad.

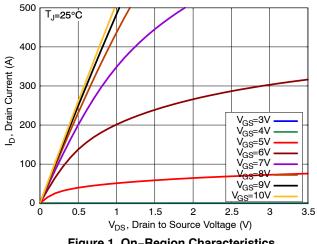
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•			•		•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	80			V
Drain-to-Source Breakdown Voltage (transient)	$\Delta V_{(BR)DSS}/ \Delta T_J$	I _D = 1 mA, Referenced to 25C		31.6		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80 V, T _J = 25°C			1	μΑ
		V _{DS} = 80 V, T _J = 125°C			250	1
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V			100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 43 A		1.9	2.1	mΩ
		V _{GS} = 6 V I _D = 21 A		2.9	3.7	1
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 213 \mu A$	2.4		3.6	V
Negative Threshold Temperature Coefficient	ΔV _{GS(TH)} / ΔT _J	$V_{GS} = V_{DS}, I_D = 213 \mu A,$		-7.5		mV/°C
Forward Transconductance	9FS	V _{DS} = 5 V, I _D = 43 A		135		S
CHARGES AND CAPACITANCES						
Input Capacitance	C _{ISS}			3800		pF
Output Capacitance	C _{OSS}	\		1100		1
Reverse Transfer Capacitance	C _{RSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		17		1
Output Charge	Q _{OSS}			79		nC
Total Gate Charge	Q _{G(TOT)}	V _{DD} = 40 V, I _D = 43 A, V _{GS} = 6 V		33		
				53		
Threshold Gate Charge	Q _{G(TH)}	V _{DD} = 40 V, I _D = 43 A, V _{GS} = 10 V		12		
Gate-to-Source Charge	Q_{GS}			18		
Gate-to-Drain Charge	Q_{GD}			8		
Gate Plateau Voltage	V_{GP}			4.7		V
Gate Resistance	R_{G}	f = 1 MHz		0.8		Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}			26		ns
Rise Time	t _r	Resistive Load, V _{GS} = 0/10 V,		9		
Turn-Off Delay Time	t _{d(OFF)}	$V_{DD} = 40 \text{ V}, I_D = 43 \text{ A}, R_G = 2.5 \Omega$		38		
Fall Time	t _f			8		
DRAIN-SOURCE DIODE CHARACTERISTIC	s					
Forward Diode Voltage	V_{SD}	I _S = 43 A, V _{GS} = 0 V, T _J = 25°C		0.82	1.2	V
		I _S = 43 A, V _{GS} = 0 V, T _J = 125°C		0.66		1
Reverse Recovery Time	t _{RR}			25		ns
Charge Time	t _a	$V_{GS} = 0 \text{ V, } I_S = 43 \text{ A,}$		14		
Discharge Time	t _b	$V_{GS} = 0 \text{ V, } I_{S} = 43 \text{ A,}$ $dIS/dt = 1000 \text{ A/}\mu\text{s, V}_{DD} = 40 \text{ V}$		11		
Reverse Recovery Charge	Q _{RR}]		183		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{5.} $R_{\theta JA}$ is determined by the user's board design.

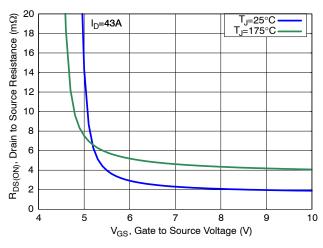
TYPICAL CHARACTERISTICS



500 $V_{DS}=5\dot{V}$ 450 400 Drain Current (A) 350 300 T_J=-55°C-T_J=25°C-T_J=175°C-250 200 ف 150 100 50 0 0 3 7 8 V_{GS}, Gate to Source Voltage (V)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



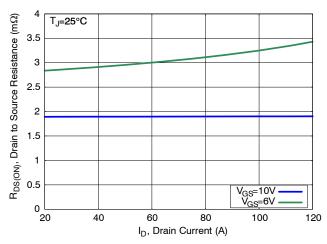
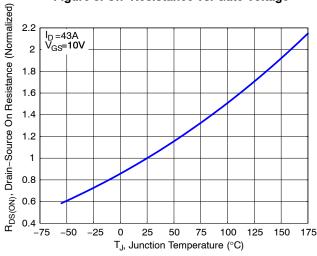


Figure 3. On-Resistance vs. Gate Voltage

Figure 4. On-Resistance vs. Drain Current



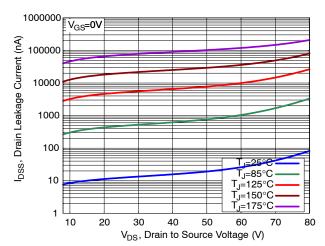


Figure 5. Normalized ON Resistance vs. **Junction Temperature**

Figure 6. Drain Leakage Current vs. Drain Voltage

TYPICAL CHARACTERISTICS

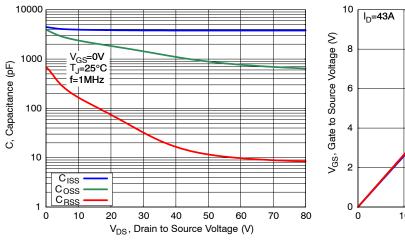
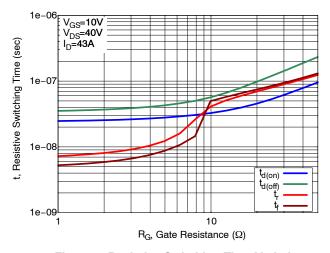


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



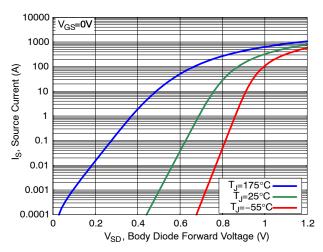
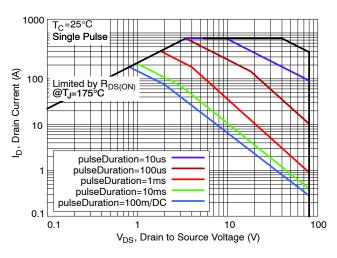


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Characteristics



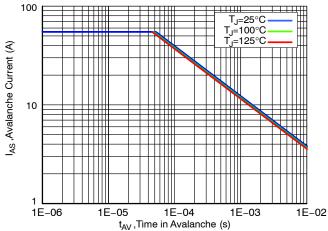
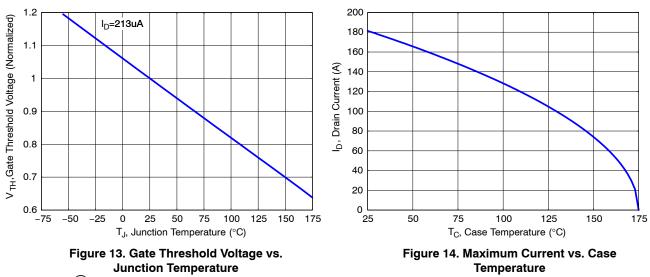


Figure 11. Safe Operating Area (SOA)

Figure 12. Avalanche Current vs Pulse Time (UIS)

TYPICAL CHARACTERISTICS



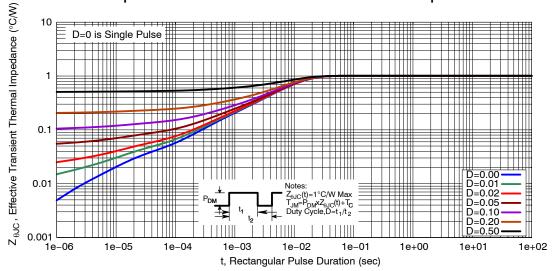


Figure 15. Transient Thermal Response





0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00		0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
E	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е		1.27 BSC			
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
M	3.00	3.40	3.80		
θ	0 °		12 °		

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

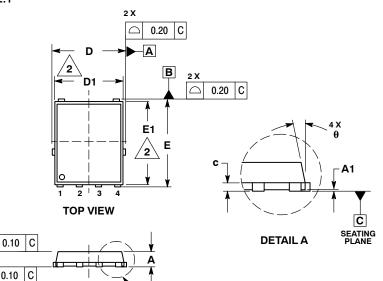
= Lot Traceability

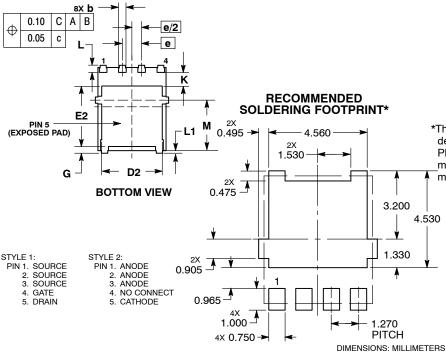
= Assembly Location Α

Υ = Year W = Work Week

ZZ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON14036D Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** DFN5 5x6, 1.27P (SO-8FL) **PAGE 1 OF 1**

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for ON Semiconductor manufacturer:

Other Similar products are found below:

041950FB 0W888-002-XTP 100307QCX 12A02CH-TL-E 15025-512-XTD 15C01C-TB-E 15C01M-TL-E 15C01SS-TL-E 15C02CH-TL-E 15C02MH-TL-E 15GN03CA-TB-E 15GN03MA-TL-E 1.5KE120ARL4 1.5KE18ARL4G 1.5KE250A 1.5KE27ARL4G 1.5KE39ARL4G 1.5KE47ARL4G 1.5SMC20AT3 1.5SMC24AT3 1.5SMC27AT3 1.5SMC39AT3 1.5SMC47AT3 1.5SMC68AT3 1.5SMC82AT3 1HN04CH-TL-W 1HP04CH-TL-W 1N3064 1N3070TR 1N3595 1N3595TR 1N4001G 1N4001RLG 1N4002G 1N4002RLG 1N4003G 1N4003RLG 1N4004RLG 1N4004RLG 1N4005G 1N4005RLG 1N4005TR 1N4005TR 1N4006FFG 1N4006G 1N4006RLG 1N4007FFG 1N4007G 1N4007RLG 1N4148 1N4148_T26A